2SK1336

Silicon N-Channel MOS FET

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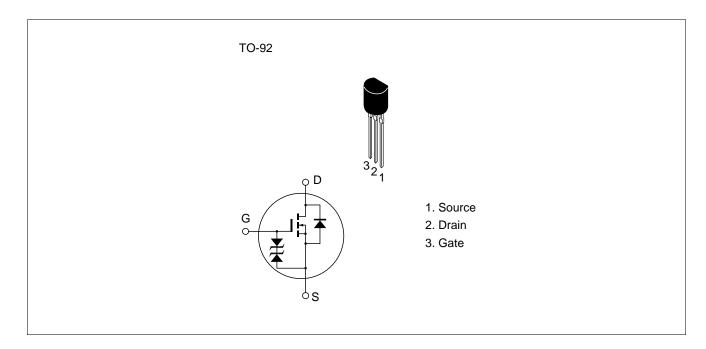
Application

High speed power switching

Features

- Low on-resistance
- High speed switching
- Low drive current
- 4 V gate drive device
 - Can be driven from 5 V source
- Suitable for motor drive, DC-DC converter, power switch and solenoid drive

Outline





2SK1336

Absolute Maximum Ratings $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit	
Drain to source voltage	V _{DSS}	60	V	
Gate to source voltage	$V_{\sf GSS}$	±20	V	
Drain current	I _D	0.3	А	
Drain peak current	I _{D(pulse)} *1	1.2	А	
Body to drain diode reverse drain current	I _{DR}	0.3	Α	
Channel dissipation	Pch	400	mW	
Channel temperature	Tch	150	°C	
Storage temperature	Tstg	-55 to +150	°C	

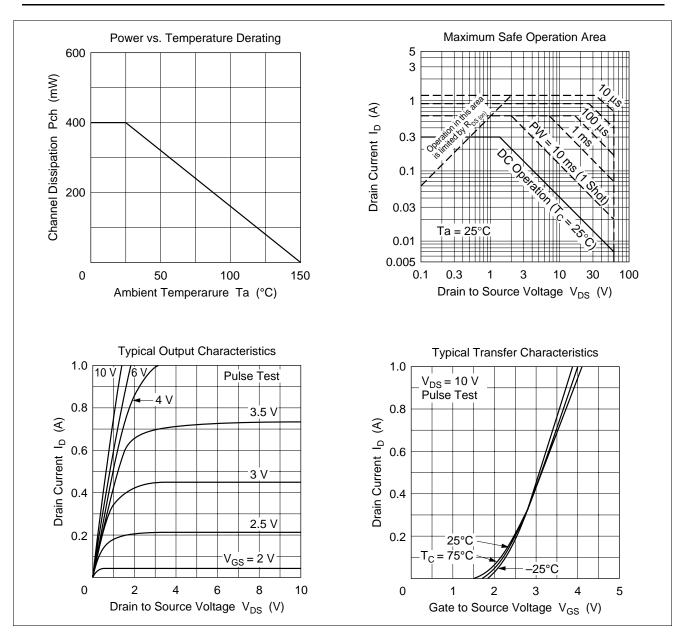
Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

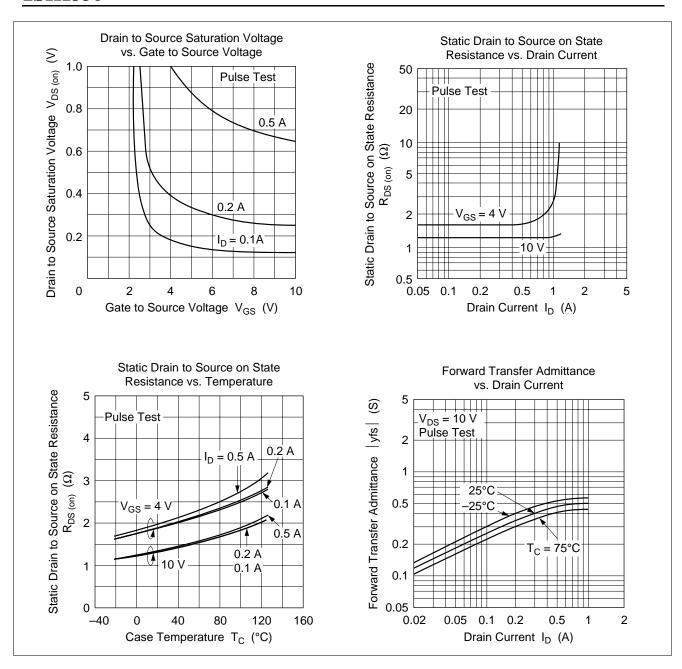
Electrical Characteristics ($Ta = 25^{\circ}C$)

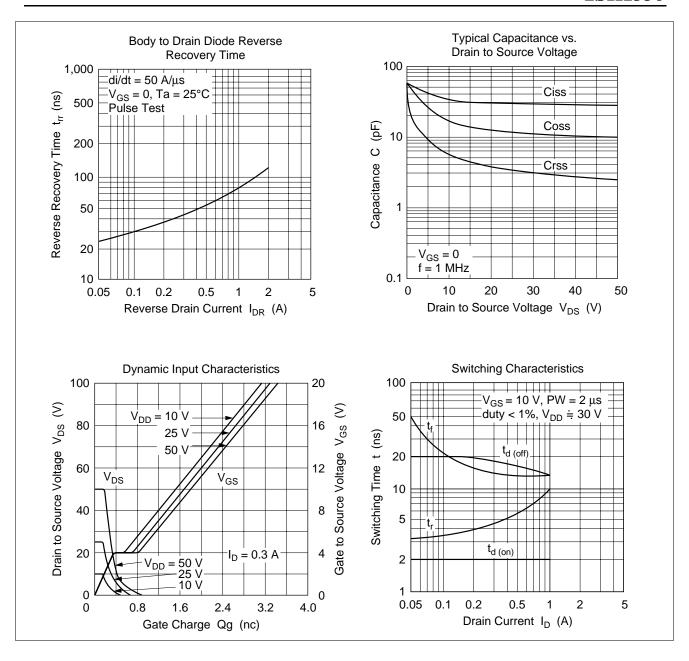
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	60	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±20	_	_	V	$I_{G} = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_	_	50	μΑ	$V_{DS} = 50 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	1.0	_	2.0	V	$I_{D} = 1 \text{ mA}, V_{DS} = 10 \text{ V}$
Static drain to source on state resistance	R _{DS(on)}	_	1.3	1.7	Ω	$I_D = 0.2 \text{ A}, V_{GS} = 10 \text{ V}^{*1}$
		_	1.8	2.5	Ω	$I_D = 0.2 \text{ A}, V_{GS} = 4 \text{ V}^{*1}$
Forward transfer admittance	yfs	0.22	0.35	_	S	$I_D = 0.2 \text{ A}, V_{DS} = 10 \text{ V}^{*1}$
Input capacitance	Ciss	_	33	_	pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0,$
Output capacitance	Coss	_	17	_	pF	f = 1 MHz
Reverse transfer capacitance	Crss	_	5	_	pF	
Turn-on delay time	t _{d(on)}	_	2	_	ns	$I_D = 0.2 \text{ A}, V_{GS} = 10 \text{ V},$
Rise time	t _r	_	4	_	ns	$R_L = 150 \Omega$
Turn-off delay time	t _{d(off)}	_	18	_	ns	
Fall time	t _f	_	16	_	ns	
Body to drain diode forward voltage	V_{DF}	_	0.9	_	V	$I_F = 0.3 \text{ A}, V_{GS} = 0$
Body to drain diode reverse recovery time	t _{rr}	_	45	_	ns	$I_F = 0.3 \text{ A}, V_{GS} = 0,$ $di_F/dt = 50 \text{ A}/\mu\text{s}$
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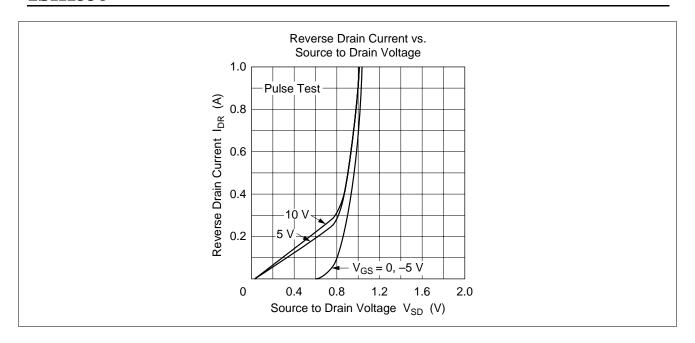
Note: 1. Pulse test

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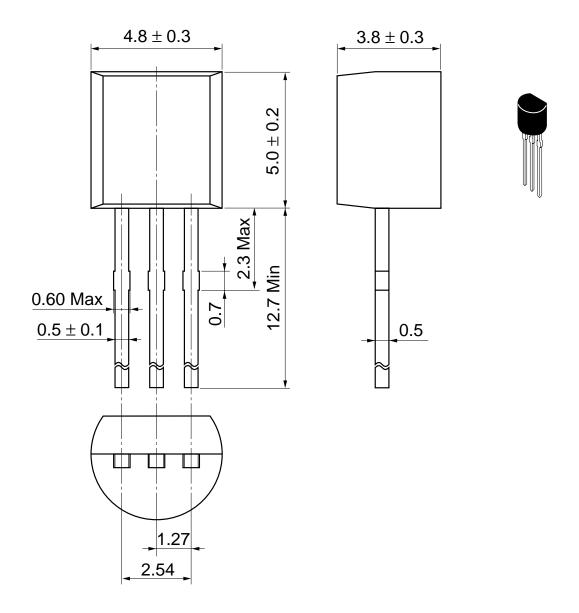








Unit: mm



Hitachi Code	TO-92 (1)
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.25 g

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